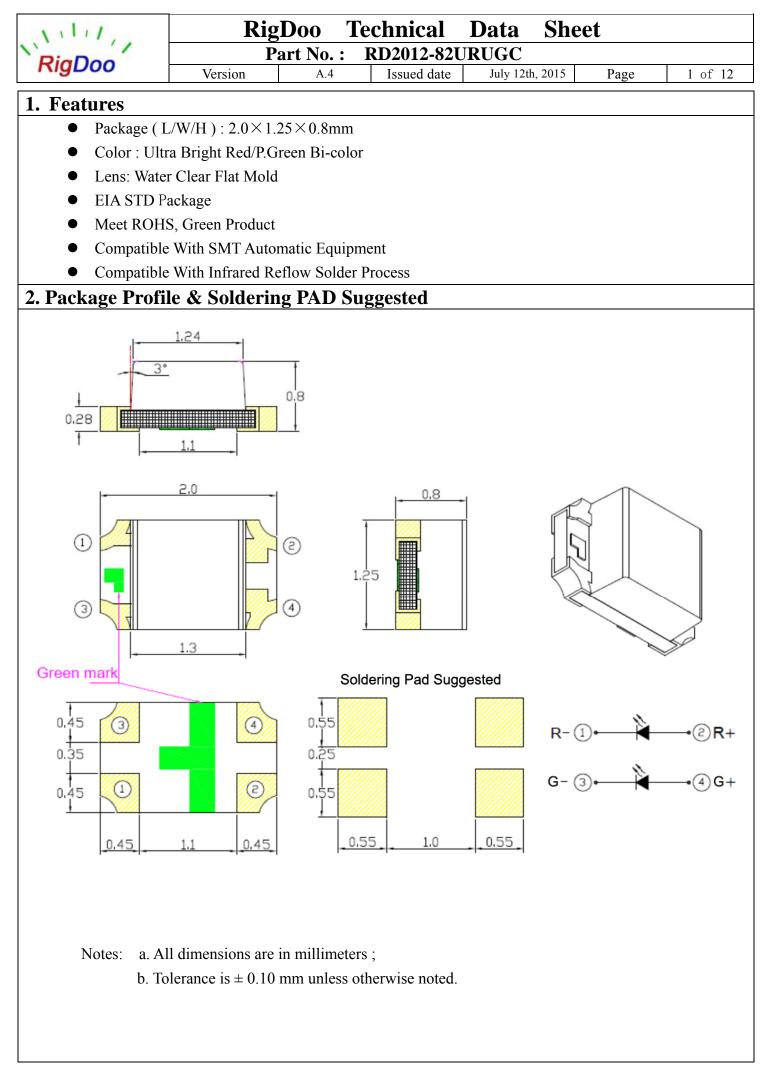


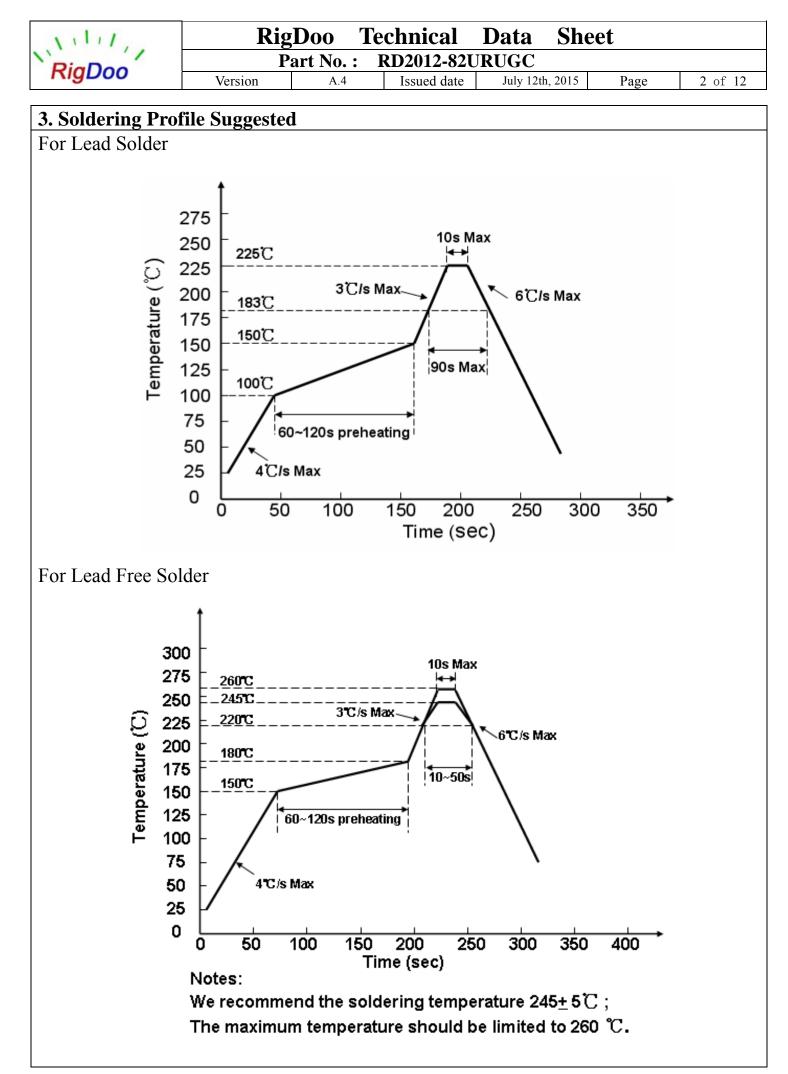
Technical Data Sheet

0805 2012 Red/P.Green Bi-Color SMD Chip LED
RD2012-82URUGC
A.4
July 12 th , 2015

Customer Approval

Instituted By:	Checked By:	Approved By:
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	E-mail: info@rigdoo.o	com
	Http://www.rigdoo.co	om







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4. Absolute Maximum Ratings At Ta=25°C

Version

Parameter	Symbol	Rating		Unit	
Dower Dissinction	Pd	UR	75	mW	
Power Dissipation	Pu	UG	75	III W	
Peak Forward Current	Inn	UR	70		
(1/10 Duty Cycle, 0.1ms Pulse Width)	Ifp	UG	70	— mA	
DC Forward Current	In	UR	25		
DC Forward Current	$I_{ m F}$	UG	25	— mA	
Devence Valtage	VR	UR	5	V	
Reverse Voltage		UG	5	- V	
Operating Temperature Range	Topr	-30°C ~ +85°C			
Storage Temperature Range	Tstg	-40°C ~ +90°C			
Soldering Condition	Tsol	Reflow soldering : 260°C For 5 Seconds Hand soldering: 300°C For 3 Seconds			
Electrostatic Discharge	ESD	2000 V		V	



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5. Electrical Optical Ta=25℃ **Characteristics** At

Version

Parameter	Symbol	Color	Min.	Тур.	Max.	Unit	Test Condition	
Lyminous Intensity	IV	UR		65		mad	IF = 5mA	
Luminous Intensity	1 V	UG		220		mcd	$I\Gamma = JIIIA$	
Dominant Wavelength	λd	UR	615-		630-		IF = 5mA	
Dominant wavelength	λü	UG	520		530-	nm	nm	$I\Gamma = JIIIA$
Dools Waxalangth	3.5	UR		630		10.100	IF = 5mA	
Peak Wavelength	λp	UG		522		nm	$I\Gamma = JIIIA$	
Spectral Line Half-Width	Δλ	UR		20			IF = 5mA	
Specual Line Han-width	$\Delta \lambda$	UG		30		nm	$I\Gamma = JIIIA$	
Forward Voltage	VF	UR	1.8		2.2	V	IF = 5mA	
Forward voltage	VГ	UG	2.6		3.2	v	$I\Gamma = JIIIA$	
Reverse Current	IR	UR			5	uA	VR=5V	
Reverse Current	IK	UG			5	uA	V N-J V	
Viewing Angle	201/2			120		deg	IF = 5mA	

Notes: 1. Luminous intensity is measured with a light sensor and filter combination that approximates the CIE eye-response curve.

- 2. θ 1/2 is the off-axis angle at which the luminous intensity is half the axial luminous intensity.
- 3. The dominant wavelength, λd is derived from the CIE chromaticity diagram and represents the single wavelength which defines the color of the device.

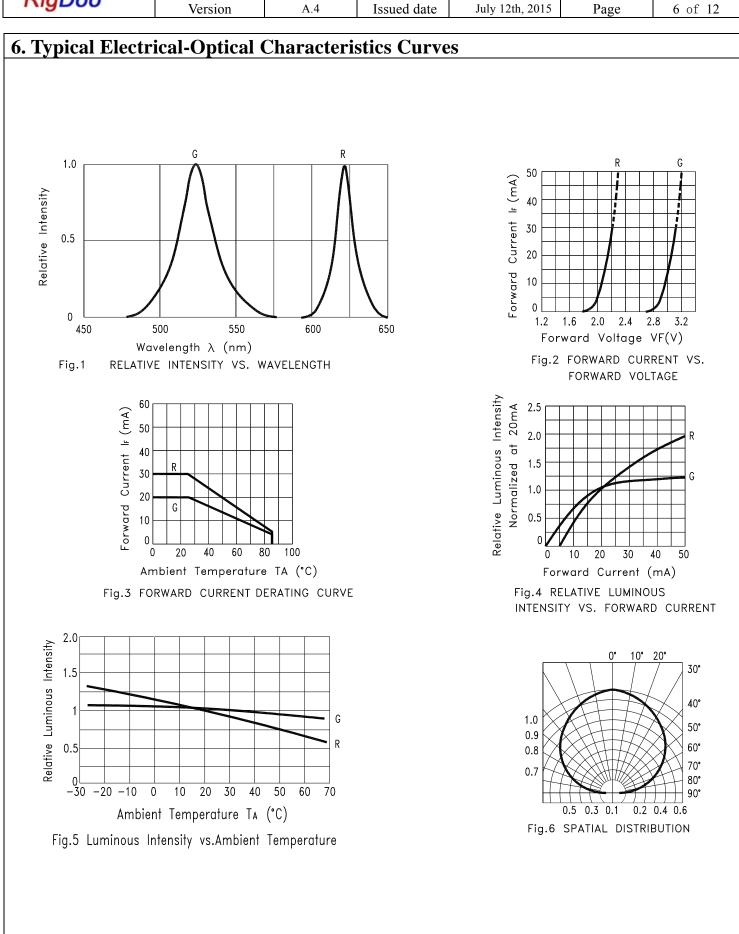
Addr.		RigDoo	Techr	ical	Data	Sheet		
RigDoo		Part No. : RD2012-82URUGC						
Rigboo	Version	I	A.4 Iss	ued date	July 12th, 2	2015	Page	5 of 12
IV-R								
Bin	Mi	n	Max		Unit	t	Cor	ndition
R1	45	;	56		MCD		IF=5mA	
R2	56)	72					
R3	72		90					
IV-UG								
Bin	Mi	n	Max		Unit	t	Cor	ndition
B1	14	0 0	180					
B2	18	0 0	230		MCI)	IF=5mA	
B3	23	0	285		-			
IF-UG Bin	Min		Max		Unit	C	Condition	
6	2.8		2.9				Condition	
7	2.9		3.0					
8	3.0		3.1	_	VI		F=5mA	
9	3.1		3.2					
IF-R	I	I						
Bin	Min		Max		Unit	Co	ndition	
1	1.8		1.9					
2	1.9		2.0				F=5mA	
3	2.0		2.1		V	IF		
4	2.1		2.2					
WLD-R								
Bin	Min	N	lax	1	Unit	Co	ndition	
А	615	(520					
В	620	(625				F=5mA	
C	625	(530					

	-			
Bin	Min	Max	Unit	Condition
В	520	523		
С	523	526	nm	IF=5mA
D	526	529		
Е				



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CPN: XXXXXX

QTY: XXXX

P/N:

RigDoo

XXXXXX

Rohs

XXXX

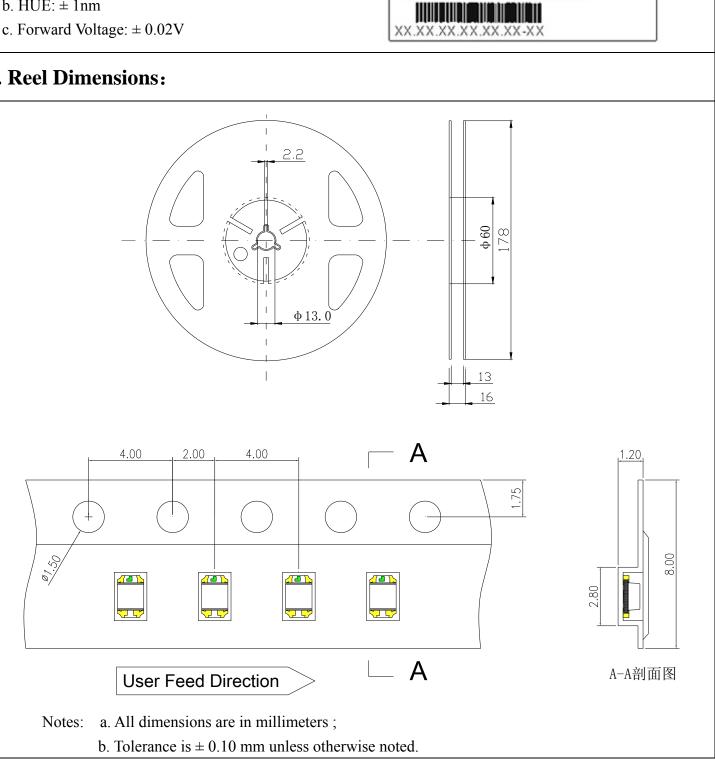
7. Label explanation

- CAT: Luminous Intensity Rank (unit: mcd)
- HUE: Dominant Wavelength Rank (unit : nm)
- REF: Forward Voltage Rank (unit: V)

Rank Tolerance:

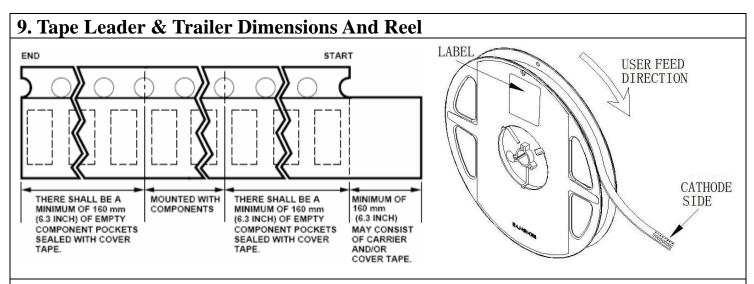
- a. Luminous Intensity: $\pm 11\%$
- b. HUE: ± 1 nm

8. Reel Dimensions:

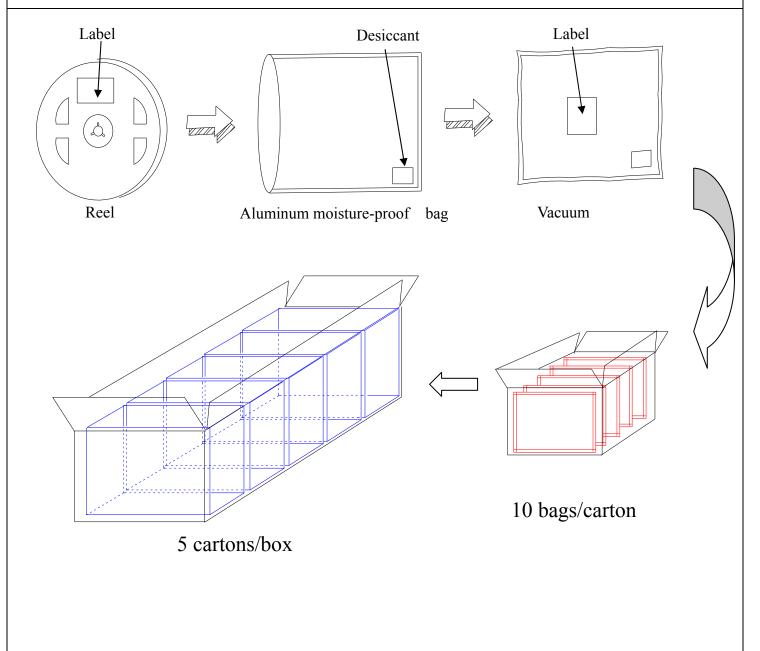




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10. Moisture Resistant Packaging:





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Classification	Test Item	Test Condition	Reference Standard	Reference Standard
	Operation Life	Ta= Under Room Temperature As Per Data Sheet Maximum Rating	1000HRS (-24HRS,+72HRS)*@20mA	MIL-STD-750D:1026 MIL-STD-883D:1005 JIS C 7021:B-1
Endurance Test	High Temperature, High Humidity Storage	IR-Reflow In-Board, 2 Times Ta= 85±5°C,RH= 85%	1000HRS±2HRS	JESD22-A101
Test	High Temperature Storage	Ta=105±5℃	1000HRS (-24HRS,+72HRS)	MIL-STD-883D:1008 JIS C 7021:B-10
	Low Temperature Storage	Ta= -55±5℃	1000HRS (-24HRS,+72H RS)	JIS C 7021:B-12
Environmental Test	Temperature Cycling	105° C ~ 25° C ~ -55° C ~ 25° C 30mins 5mins 30mins 5mins	10 Cycles	MIL-STD-202F:107D MIL-STD-750D:1051 MIL-STD-883D:1010 JIS C 7021:A-4
	Thermal Shock	IR-Reflow In-Board, 2 Times $85 \pm 5^{\circ}$ C $\sim -40^{\circ}$ C $\pm 5^{\circ}$ C10mins10mins	10 Cycles	MIL-STD-202F:107D MIL-STD-750D:1051 MIL-STD-883D:1011
	Solder Resistance	$T.sol=260 \pm 5^{\circ}C$	$10 \pm 1 \text{secs}$	MIL-STD-202F:210A MIL-STD-750D:2031 JIS C 7021:A-1
	IR-Reflow Normal Process	Ramp-up rate(183°C to Peak) +3°C/ second max Temp. maintain at 125(±25)°C 120 seconds max Temp. maintain above 183°C 60-150 seconds Peak temperature range 235°C+5/-0°C Time within 5°C of actual Peak Temperature (tp) 10-30 seconds Ramp-down rate +6°C/second max		MIL-STD-750D:2031. J-STD-020C
	IR-Reflow Pb Free Process	Ramp-up rate(217°C to Peak) +3°C/ second max Temp. maintain at 175(±25)°C 180 seconds max Temp. maintain above 217°C 60-150 seconds Peak temperature range 260°C+0/-5°C Time within 5°C of actual Peak Temperature (tp) 20-40 seconds Ramp-down rate +6°C/second max		MIL-STD-750D:2031. J-STD-020C
	Solderability	T.sol= 235 ± 5 °C Immersion rate 25±2.5 mm/sec Coverage ≥95% of the dipped surface	Immersion time 2±0.5 sec	MIL-STD-202F:208D MIL-STD-750D:2026 MIL-STD-883D:2003 IEC 68 Part 2-20



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12. Cautions

Storage

- 1.Before opening original package, it is recommended to store them in the following environment: Temperature: 5°C~30°C, Humidity: 85%RH max. When the inventory over 2 months, Should be done before treatment using dehumidification, Temperature: 60°C/8 hours.
- 2. After opening original package, the storage ambient for the LEDs should be in 5~30°C temperature and 60% or less relative humidity.
- 3. In order to avoid moisture absorption, it is recommended that the LEDs that out of the original package should be stored in a sealed container with appropriate desiccant, or in desiccators with nitrogen ambient.
- 4. The LEDs should be used within 168hrs (7 days) after opening the package. Once been mounted, soldering should be quick.
- 5. If the moisture absorbent material (silica gel) has faded away or the LEDs stored out of original package for more than 168hrs (7 days), baking treatment should be performed using the conditions: 60°C at least 24 hours.

ESD (Electrostatic Discharge)-Protection

A LED (especially the Blue, White and Green product) is an ESD sensitive component, and static electricity or power surge will damage the LED. ESD-damaged LEDs will exhibit abnormal characteristics such as high reverse leakage current, low forward voltage, or "no light-up" at low currents, etc. Some advice as below should be noticed:

- 1. A conductive wrist strap or anti-electrostatic glove should be worn when handling these LEDs.
- 2. All devices, equipment, machinery, work tables and storage racks, etc. must be properly grounded
- (Grounding impedance value within 10Ω).
- 3. Use anti-static package or boxes to carry and storage LEDs. And ordinary plastic package or boxes is forbidden to use.
- 4. Use ionizer to neutralize the static charge during handling or operating.
- 5. All surfaces and objects within 1 ft close to LEDs measure less than 100V.

Cleaning

Use alcohol-based cleaning solvents such as IPA (isopropyl alcohol) to clean LEDs if necessary.

Soldering

- 1. Soldering condition refer to the draft "Soldering Profile Suggested" on page 1.
- 2. Reflow soldering should not be done more than 2 times.
- 3. Manual soldering is only suggested on repair and rework. The maximum soldering temperature should not exceed 300°C within 3 sec. And the maximum capacity of soldering iron is 30W in power.
- 4. During the soldering process, do not touch the lens at high temperature.
- 5. After soldering, any mechanical force on the lens or any excessive vibration shall not be accepted to apply, also the circuit board shall not be bent as well.



Others

- 1. The LEDs described here are intended to be used for ordinary electronic equipment (such as office equipment, communication equipment and household applications). Consult RigDoo's Sales in advance for the applications in which exceptional reliability is required, particularly when the failure or malfunction of the LEDs may directly jeopardize life or health. (such as in aviation, transportation, traffic control equipment, medical and life support systems and safety devices).
- 2. The light output from the high luminous intensity LEDs may cause injury to human eyes when viewed directly.
- 3. The appearance and specifications of the product may be modified for improvement without prior notice.